

February 2012
UniFET

FDB12N50F

N-Channel MOSFET, FRFET 500V, 11.5A, 0.7Ω

Features

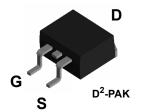
- $R_{DS(on)} = 0.59\Omega$ (Typ.)@ $V_{GS} = 10V$, $I_D = 6A$
- Low gate charge (Typ. 21nC)
- Low C_{rss} (Typ. 11pF)
- · Fast switching
- · 100% avalanche tested
- · Improve dv/dt capability
- · RoHS compliant

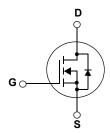


Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advance technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switching mode power supplies and active power factor correction.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol		Parameter		Ratings	Units
V_{DSS}	Drain to Source Voltage			500	V
V_{GSS}	Gate to Source Voltage			±30	V
	Drain Current	-Continuous (T _C = 25°C)		11.5	^
I _D	DrainGuirent	-Continuous (T _C = 100°C)		6.9	Α
I _{DM}	Drain Current	- Pulsed	- Pulsed (Note 1)		Α
E _{AS}	Single Pulsed Avalanche Er	nergy	(Note 2)	456	mJ
I _{AR}	Avalanche Current		(Note 1)	11.5	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	16.5	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns
6	Dawer Dissination	$(T_C = 25^{\circ}C)$		165	W
P_D	Power Dissipation	- Derate above 25°C		1.33	W/°C
T _J , T _{STG}	Operating and Storage Tem	perature Range		-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	Ratings	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.75	°C/W
R_{\thetaJA}	Thermal Resistance, Junction to Ambient	62.5	C/VV

Package Marking and Ordering Information $T_C = 25^{\circ}C$ unless otherwise noted

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB12N50F	FDB12N50FTM_WS	D2-PAK	330mm	24mm	800

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu A$, $V_{GS} = 0V$, $T_J = 25^{\circ}C$	500	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	-	0.5	-	V/°C
1	Zero Gate Voltage Drain Current	V _{DS} = 500V, V _{GS} = 0V	-	-	10	μА
IDSS	Zelo Gale Vollage Diam Current	$V_{DS} = 400V, T_{C} = 125^{\circ}C$	-	-	100	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 6A$	-	0.59	0.7	Ω
g _{FS}	Forward Transconductance	$V_{DS} = 40V, I_D = 6A$ (Note 4)	-	12	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V f = 1MHz		-	1050	1395	pF
Coss	Output Capacitance			-	135	180	pF
C _{rss}	Reverse Transfer Capacitance	1 - 111112		-	11	17	pF
Q _{g(tot)}	Total Gate Charge at 10V			-	21	30	nC
Q_{gs}	Gate to Source Gate Charge	V _{DS} = 400V, I _D = 11.5A		-	6	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	V _{GS} = 10V	(Note 4, 5)	-	9	-	nC

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	21	50	ns
t _r	Turn-On Rise Time	V _{DD} = 250V, I _D = 11.5A		-	45	100	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25\Omega$		-	50	110	ns
t _f	Turn-Off Fall Time		(Note 4, 5)	-	35	80	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	-	11.5	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	-	46	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _{SD} = 11.5A		-	-	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 11.5A		-	134	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	(Note 4)	1	0.37	-	μС

- **Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 6.9mH, I $_{AS}$ = 11.5A, V $_{DD}$ = 50V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25 $^{\circ}$ C
- 3. $I_{SD} \le 11.5 A$, di/dt $\le 200 A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting T_J = 25°C
- 4. Pulse Test: Pulse width $\leq 300 \mu s, \, Duty \, Cycle \leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

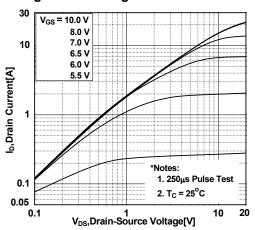


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

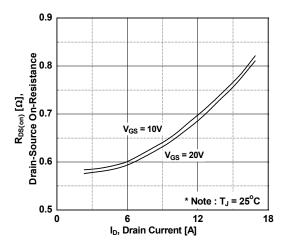


Figure 5. Capacitance Characteristics

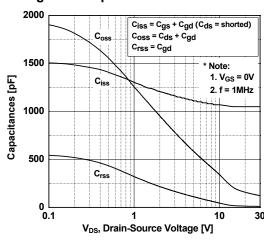


Figure 2. Transfer Characteristics

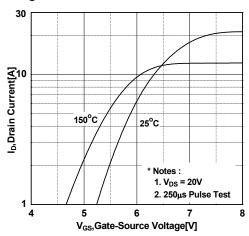


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

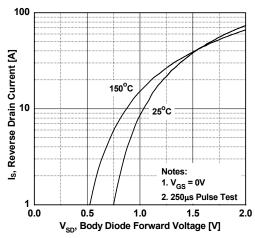
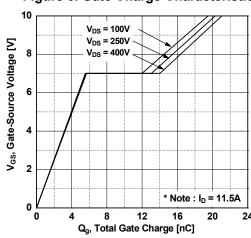


Figure 6. Gate Charge Characteristics



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Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

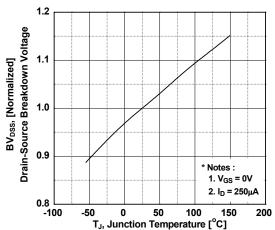


Figure 8. Maximum Safe Operating Area

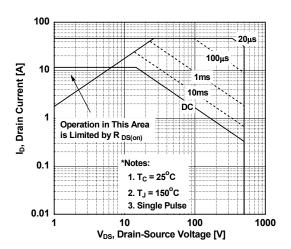


Figure 9. Maximum Drain Current vs. Case Temperature

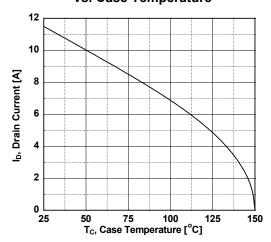
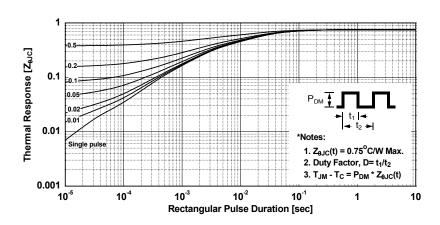
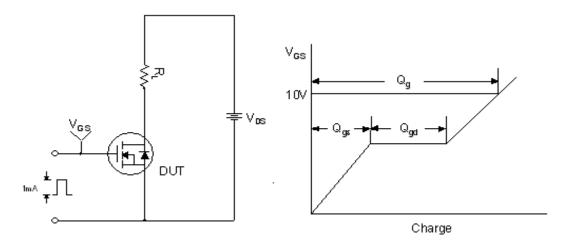


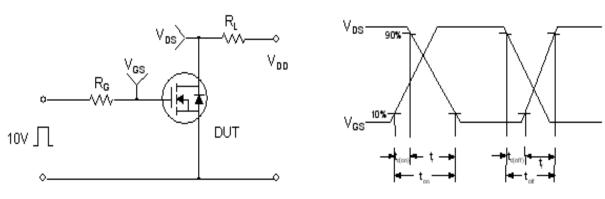
Figure 10. Transient Thermal Response Curve



Gate Charge Test Circuit & Waveform

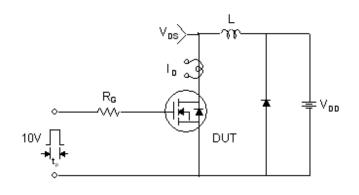


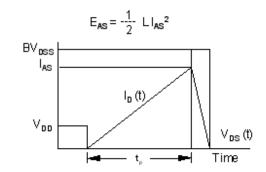
Resistive Switching Test Circuit & Waveforms



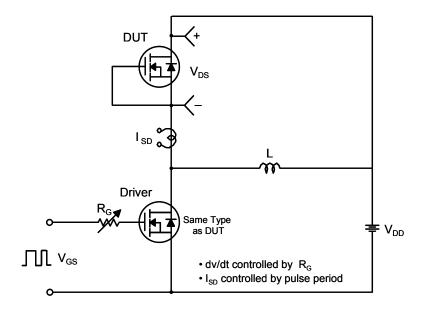
Unclamped Inductive Switching Test Circuit & Waveforms

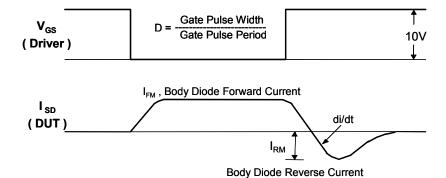
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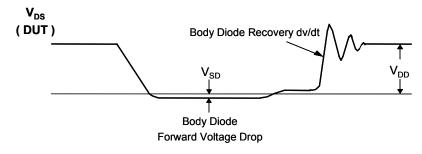




Peak Diode Recovery dv/dt Test Circuit & Waveforms

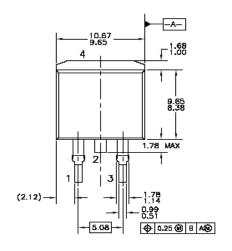


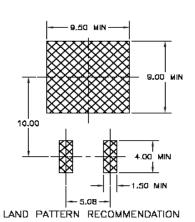


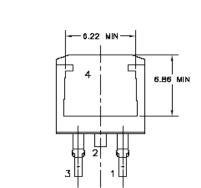


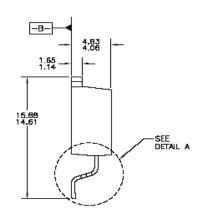
Mechanical Dimensions

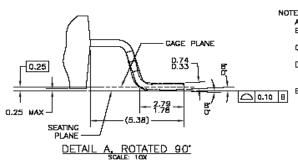
D2-PAK











TO283AD2REVD

- NOTES: UNLESS OTHERWISE SPECIFIED

 A) ALL DIMENSIONS ARE IN MILLIMETERS.

 B) REFERENCE JEDEC, TO—263, ISSUE D, VARIATION AB, DATED JULY 2003.

 C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5M 1982.

 D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).

 B) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.

Dimensions in Millimeters





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